L Number	Hits	Search Text	DB	Time stamp
1	2	5824599.pn. 6020266.pn.	USPAT;	2004/03/04 15:39
			US-PGPUB	
2	3585	257/412.ccls. 257/413.ccls. 257/762.ccls. 257/766.ccls.	USPAT;	2004/03/04 16:33
		257/768.ccls. 257/769.ccls. 257/774.ccls.	US-PGPUB	0004/00/51 :== :=
3	0	(257/412.ccls. 257/413.ccls. 257/762.ccls. 257/766.ccls.	USPAT;	2004/03/04 17:18
		257/768.ccls. 257/769.ccls. 257/774.ccls.) and ((gate with	US-PGPUB	
		(platinum pt rhodium rh ruthenium ru iridium ir osmium os))		
		same ((plug interconnect wiring trace via contact) with		
	118	(copper cu)) same (source drain)) (257/412.ccls. 257/413.ccls. 257/762.ccls. 257/766.ccls.	USPAT;	2004/03/04 16:39
4	110	257/768.ccls. 257/769.ccls. 257/762.ccls.) and (gate with	US-PGPUB	2004/03/04 10.39
		(platinum pt rhodium rh ruthenium ru iridium ir osmium os))	05 / 0/ 00	
5	14	''	USPAT;	2004/03/04 16:39
		257/768.ccls. 257/769.ccls. 257/774.ccls.) and (polysilicon	US-PGPUB	
		with gate with (platinum pt rhodium rh ruthenium ru iridium		
		ir osmium os))		
6	15	((gate with (platinum pt rhodium rh ruthenium ru iridium ir	USPAT;	2004/03/04 16:55
		osmium os)) same ((plug interconnect wiring trace via	US-PGPUB	
		contact) with (copper cu)) same (source drain))		
7	35	(257/412.ccls. 257/413.ccls. 257/762.ccls. 257/766.ccls.	USPAT;	2004/03/04 17:28
		257/768.ccls. 257/769.ccls. 257/774.ccls.) and (gate same	US-PGPUB	
		((plug interconnect wiring trace via contact) with (copper		
	200	cu)) same (source drain))	LICDAT	2004/03/04 17:29
8	380	(gate same ((plug contact) with (copper cu)) same (source	USPAT; US-PGPUB	2004/03/04 17:29
9	13	drain)) (gate with ((plug contact) near2 (copper cu)) with (source	USPAT;	2004/03/04 17:34
	13	(gate with ((plug contact) hear2 (copper cu)) with (source drain))	US-PGPUB	2001/05/01 17.51
10	26	438/620.ccls. and ((plug contact) with (copper cu))	USPAT;	2004/03/04 17:36
10	20	130/020.ccis. and ((plug contact) man (copper cay)	US-PGPUB	200 1, 00, 01 27 100
11	547	(257/412.ccls. 257/413.ccls. 257/762.ccls. 257/766.ccls.	USPAT;	2004/03/04 18:05
		257/768.ccls. 257/769.ccls. 257/774.ccls.) and ((copper cu	US-PGPUB	
		silver ag gold au platinum pt) same ((rhodium rh ruthenium		
		ru iridium ir osmium os platinum pt) with (palladium pd		
		cobalt co nickel ni titanium ti)))		
12	1	((insulat\$4 dielectric oxide dioxide nitride interlayer) with	EPO; JPO;	2004/03/04 18:06
		(silicon si)) and ((unit adj cell) (lattice near4 (constant	DERWENT;	
		mismatch\$4 match\$4))) and ((atom\$2 near (radius radii))	IBM_TDB	
13	דכ	(bond\$4 near energy)) ((atom\$2 near (radius radii)) (bond\$4 near energy)) and	EPO; JPO;	2004/03/04 18:06
12	21	((atoms 2 hear (radius radii)) (bolids 4 hear energy)) and (semiconductor silicon si wafer substrate) and (copper cu)	DERWENT;	200 17 00 70 7 10.00
		and (rhodium rh ruthenium ru iridium ir osmium os platinum	IBM_TDB	
		pt)		
14	7	(semiconductor silicon si wafer substrate) and	USPAT;	2004/03/04 18:08
		((interconnect\$5 metal\$1is\$7 metal\$1iz\$7) same ((platinum	US-PGPUB	· ·
		pt) near4 (film layer multilayer bilayer trilayer "bi-layer"		
		"tri-layer" "multi-layer")) same ((osmium os) with (palladium		
		pd cobalt co nickel ni titanium ti) with (film layer multilayer		
		bilayer trilayer "bi-layer" "tri-layer" "multi-layer")))		2004/02/04 : 2 : :
15	241	((atom\$2 near (radius radii)) (bond\$4 near energy)) and	USPAT;	2004/03/04 18:11
		(semiconductor silicon si wafer substrate) and ((copper cu)	US-PGPUB	
		same (rhodium rh ruthenium ru iridium ir osmium os platinum pt) same (film layer multilayer bilayer trilayer		
		platinum pt) same (min layer multilayer bilayer trilayer "bi-layer" "tri-layer" "multi-layer"))		
17	199	(semiconductor silicon si wafer substrate) and ((insulat\$4	USPAT;	2004/03/04 18:11
*′		dielectric oxide dioxide nitride interlayer) with (silicon si))	US-PGPUB	
		and ((unit adj cell) (lattice near4 (constant mismatch\$4		
		match\$4))) and ((atom\$2 near (radius radii)) (bond\$4 near		
		energy))		

18	365	(semiconductor silicon si wafer substrate) and ((interconnect\$5 metal\$1is\$7 metal\$1iz\$7) same ((copper cu silver ag gold au) near4 (film layer multilayer bilayer trilayer "bi-layer" "tri-layer" "multi-layer")) same ((rhodium rh ruthenium ru iridium ir osmium os platinum pt) with (palladium pd cobalt co nickel ni titanium ti) with (film layer multilayer bilayer trilayer "bi-layer" "tri-layer" "multi-layer") with (element constituent consist\$3 compris\$3 atom	USPAT; US-PGPUB	2004/03/04 18:11
16	135	metal)))	EPO; JPO; DERWENT; IBM_TDB	2004/03/04 18:20